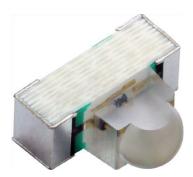


High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



DESCRIPTION

VSMB14940 is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted PCB based package (with lens) for surface mounting (SMD).

APPLICATIONS

- · Emitter for remote control
- IR touch panels
- Photointerrupters
- · Optical switch

FEATURES

Package type: surface mount

· Package form: side view

Dimensions (L x W x H in mm): 3.2 x 2.51 x 1.2

Peak wavelength: λ_p = 940 nm

High reliability

· High radiant power

· Very high radiant intensity

• Angle of half intensity: $\varphi = \pm 9^{\circ}$

· Suitable for high pulse current operation

Floor life: 168 h, MSL 3, according to J-STD-020

· Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





RoHS HALOGEN

FREE **GREEN**

•	IR touch	nanale	

PRODUCT SUMMARY					
COMPONENT	I _e (mW/sr)	φ (deg)	λ _p (nm)	t _r (ns)	
VSMB14940	35	± 9	940	15	

Note

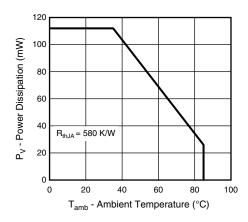
· Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VSMB14940	Tape and reel	MOQ: 1500 pcs, 1500 pcs/reel	Side view		

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
Reverse voltage		V _R	5	V		
Forward current		I _F	70	mA		
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA		
Power dissipation		P _V	112	mW		
Junction temperature		T _j	100	°C		
Operating temperature range		T _{amb}	-40 to +85	°C		
Storage temperature range		T _{stg}	-40 to +100	°C		
Soldering temperature	According fig. 10, J-STD-020	T _{sd}	260	°C		
Thermal resistance junction / ambient	J-STD-051, soldered on PCB	R _{thJA}	580	K/W		



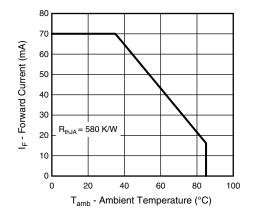
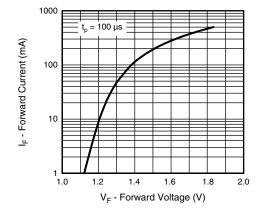


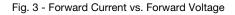
Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

Fig. 2 - Forward Current Limit vs. Ambient Temperature

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	V_{F}	1.05	1.24	1.5	V
Forward voltage	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	V_{F}	-	1.33	1.6	V
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	V_{F}	-	1.8	-	V
Temperature coefficient of V _F	I _F = 20 mA	TK _{VF}	-	-1.12	-	mV/K
Reverse current	V _R = 5 V	I _R	-	-	10	μΑ
Junction capacitance	$V_R = 0 \text{ V, f} = 1 \text{ MHz, E} = 0 \text{ mW/cm}^2$	CJ	-	38	-	pF
	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	l _e	6.5	10.5	14.5	mW/sr
Radiant intensity	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	l _e	-	35	-	mW/sr
	$I_F = 500 \text{ mA}, t_p = 100 \mu \text{s}$	l _e	-	205	-	mW/sr
Radiant power	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	φe	-	28	-	mW
Temperature coefficient of radiant power	I _F = 20 mA	ТКфе	=	0.39	-	%/K
Angle of half intensity		φ	-	± 9	-	deg
Peak wavelength	I _F = 70 mA	λ_{p}	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ	-	30	-	nm
Temperature coefficient of λ_p	I _F = 30 mA	TKλ _p	-	0.30	-	nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r	-	15	-	ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f	-	15	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)





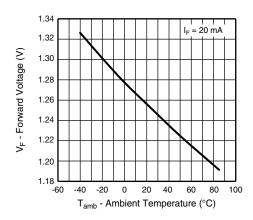


Fig. 4 - Forward Voltage vs. Ambient Temperature



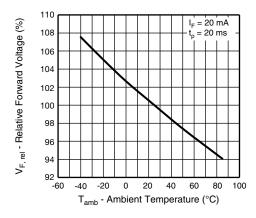


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

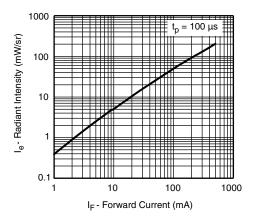


Fig. 6 - Radiant Intensity vs. Forward Current

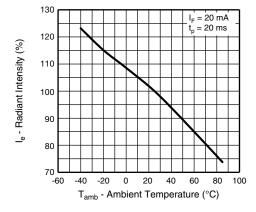


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

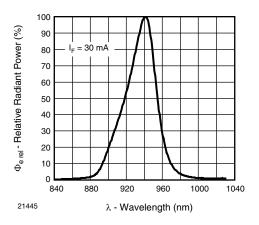


Fig. 8 - Relative Radiant Power vs. Wavelength

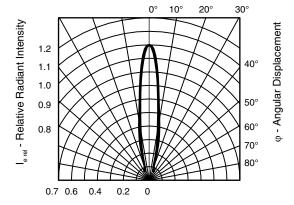


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement



SOLDER PROFILE

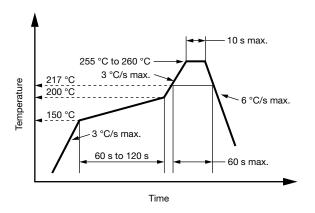


Fig. 10 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

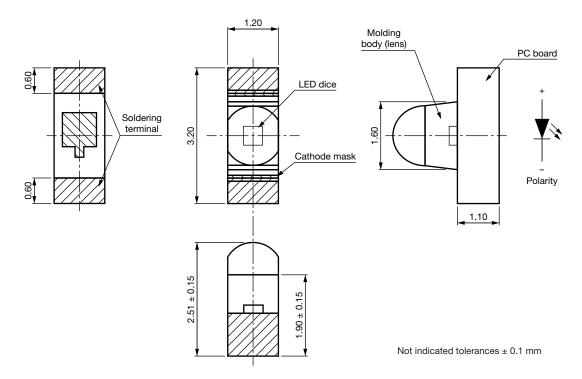
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, according to J-STD-020.

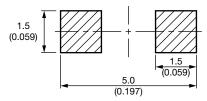
DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.

PACKAGE DIMENSIONS in millimeters: VSMB14940

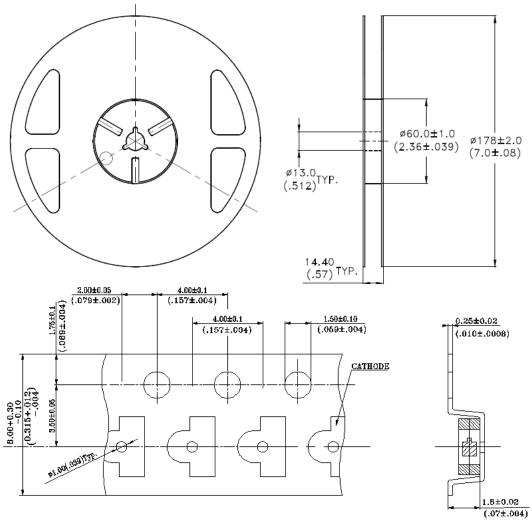


Recommended Solder Pad





TAPING AND REEL DIMENSIONS in millimeters: **VSMB14940**





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Vishay

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